# DB3X315E

### Silicon epitaxial planar type

For high speed switching circuits

#### Features

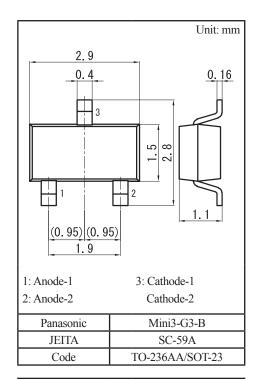
- Short reverse recovery time  $t_{rr}$
- Small reverse current  $I_R$
- Halogen-free / RoHS compliant
- (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)
- Marking Symbol: 5D

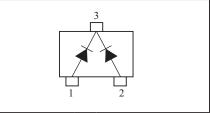
#### Packaging

 $DB3X315E0L \ \ Embossed \ type \ (Thermo-compression \ sealing): \ 3\ 000 \ pcs \ / \ reel \ (standard)$ 

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit		
Reverse voltage	V <sub>R</sub>	30	V		
Maximum peak reverse volta	V <sub>RM</sub>	30	V		
Forward current	Single	T	30	mA	
	Double *1	- I <sub>F</sub>	20		
Peak forward current	Single	т	150	mA	
	Double *1	- I <sub>FM</sub>	110		
Junction temperature	Tj	125	°C		
Operating ambient temperature		T <sub>opr</sub>	-40 to +85	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C		





Note) \*1: Value of each diode in double diodes used.

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

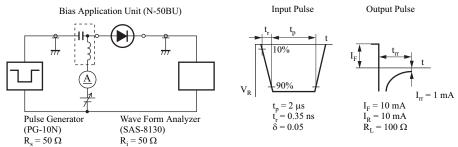
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F1</sub>	$I_F = 1 \text{ mA}$			0.4	V
	V <sub>F2</sub>	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I <sub>R</sub>	$V_R = 30 V$			300	nA
Terminal capacitance	Ct	$V_R = 10 V_r f = 1 MHz$		1.4		pF
Reverse recovery time *1	t <sub>rr</sub>	$I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$		1.0		ns

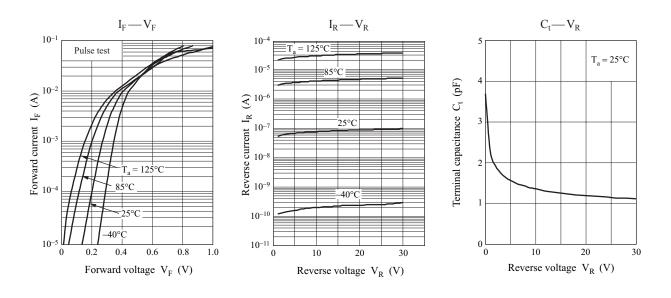
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 2 GHz

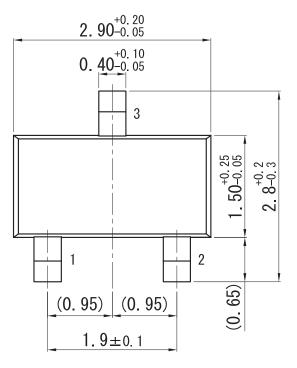
\*1: t<sub>rr</sub> measurement circuit

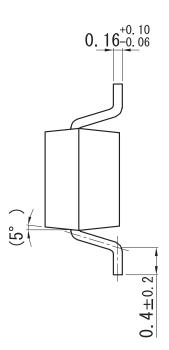


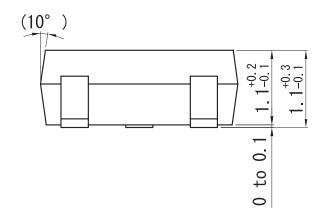


Unit: mm

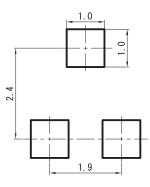
## Mini3-G3-B







Land Pattern (Reference) (Unit: mm)



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